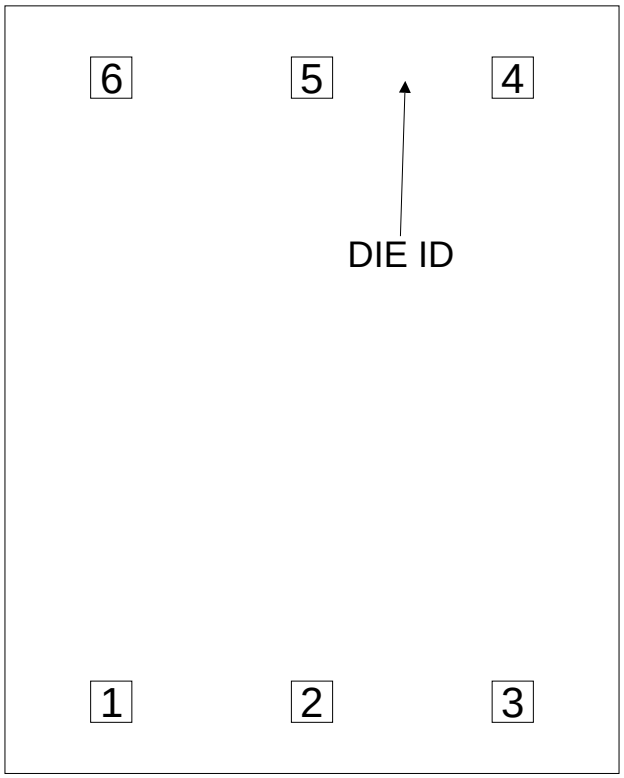
LM71A MDO MCD5010A
1.5C ACCURACY, SPI DIGITAL INTERFACE

26-Aug-2010

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM71A	Bond Pad Opening Size (min)	68.20µm x 68.20µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	203.2mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1016.00µm x 1270.00µm 40.0mils x 50.0mils	Back Side Connection	Floating
Thickness	0.0µm Nominal		
Min Pitch	332.15µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(A-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
CS/	1	-332.15	-516.30	68.20	x	68.20
GND	2	0.00	-516.30	68.20	x	68.20
V+	3	332.15	-516.30	68.20	x	68.20
SC	4	332.15	516.30	68.20	x	68.20
GND	5	0.00	516.30	68.20	x	68.20
SIO	6	-332.15	516.30	68.20	x	68.20

Notes

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